

ESTC 2020, Vestfold (Norway), 15-18 September 2020, going virtual.

Open for registration

The Electronics System-Integration Technology Conferences (ESTC) is the premier European conference on Electronics System-Integration and Packaging, forming together with ECTC and EPTC IEEE EPS's "flagship conferences". A biannual event since 2006, ESTC 2020 will be hosted by University of South-Eastern Norway (USN) in Vestfold. Vestfold is the "Electronic Coast" of Norway, hosting the major industry cluster in the nation for high-end electronics, particularly for aerospace, medical, maritime and industrial applications. Due to COVID-19 travel restrictions, ESTC 2020 will be carried out 100% virtual, live! The live format will allow interaction similar to an in-person conference. The digital format will give new possibilities, such as recording of presentations allowing to catch up presentations in parallel sessions.

Registration is now open (<https://www.estc-conference.net/estc-2020/registration-1>), with a deadline 10 August. The registration fee is a fraction of a normal conference registration fee.

ESTC 2020 will host an innovative virtual exhibition. Exhibitors are welcome to sign up, and we are no longer restricted by floor space. The revised Call for Exhibitors, adapted to virtual exhibition, is found here: https://www.estc-conference.net/fileadmin/documents/ESTC2020_CfE03.pdf. The digital format allows new ways of sponsoring the conference with high visibility, please find the revised Call for Sponsors here: https://www.estc-conference.net/fileadmin/documents/ESTC2020_CfS02.pdf.

ESTC 2020 can promise a very interesting programme, a sketch is published: <https://www.estc-conference.net/estc-2020/conference-schedule>. Highlights include:

5 keynotes:

- **Autonomous Shipping**: Lars Kristian Moen, Kongsberg Maritime, Norway
- **Quantum Computing with Near-Term Devices**: Andreas Fuhrer, IBM Zurich, Switzerland
- **Agriculture 4.0: Development of Smart Sensors Systems for Sustainable Food Production**: Alan O'Riordan, Tyndall National Institute, Cork, Ireland
- **Fan-out Wafer and Panel Level Packaging and the Changing Packaging Landscape**: Tanja Braun, Group Manager Fraunhofer IZM Berlin, Germany
- **Using Artificial Intelligence Methods to Ensure Electronics System Reliability**: Michael Pecht, Director of CALCE, University of Maryland, USA

Special session - The end of Moore's Law; the future is bright:

- **Post Moore's Law and Quantum Electronics**: Rao Tummala, PRC, Georgia Institute of Technology, USA
- **Can Matter Waves Save Moore?:** Bodil Holst, University of Bergen, Norway

Heterogeneous Integration Roadmap (HIR) session:

- Organized by William Chen, ASE Group, USA

On behalf of the Executive Committee, we welcome you to the virtual, live, ESTC 2020!

Knut E. Aasmundtveit
University of South-Eastern Norway
General Chair

Kristin Imenes
University of South-Eastern Norway
Executive Chair

Paul Svasta
CETTI, Romania
Technical Program Chair

